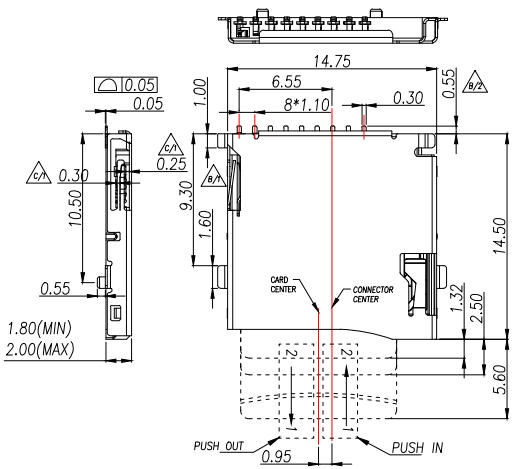
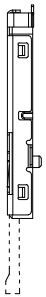
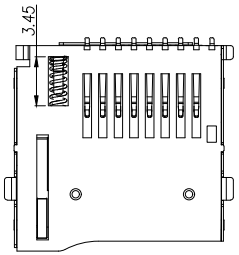
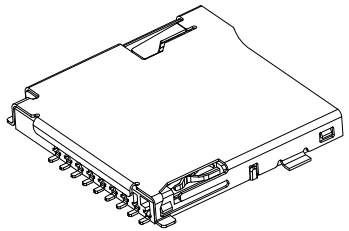
REV.	DESCRIPTION	ECN NO.	NAME	DATE









Specification:

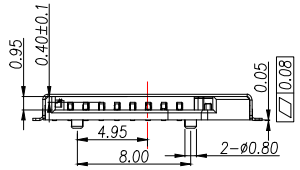
1.Electrical Characteristics:
- Contact Current Rating:0.5 Amperes.
- Dielectric Withstanding Voltage:AC500V r.m.s.
- Insulation Resistance:1000 MΩ Minimum.
- Contact Resistance:40 mΩ Maximum.

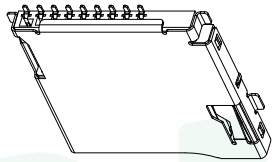
2.Environmental:
- Operating Temperature:−25°C~+90°C.

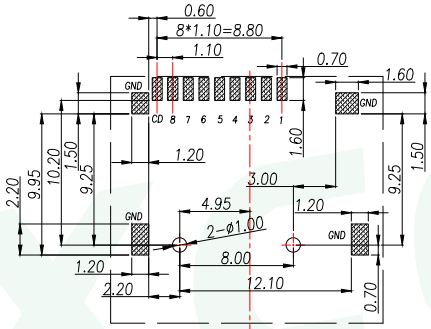
3.Environmental:
- Mating Cyeles:5,000 Insertions.

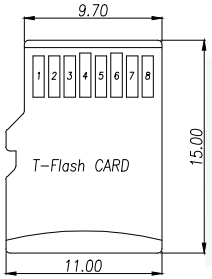
4.Mechanical Characteristics:
- Card Push Insertion/Out Force:0.2~1.40kgf.
- Contact Separation Force:0.20kgf Minimum.

5.Material:
- Insulator:HI−Temp Plastic UL 94V−0 Rated.
- Cantact:Copper Alloy(t=0.15mm).
- Shell:Stainless Steel(t=0.15mm).
- Spring:SWP.









PAD AREA

KEEP OUT AREA

RECOMMENDED PCB LAYOUT

GENERAL TOLERANCE ±0.05

Circuit Diagram for Detect Switch

WITHOUT CARD	OPEN	OPEN CD GND
INSERTING CARD	CLOSE	CLOSE CD GND

TF CARD PIN DEFINE

PIN NO.	NAME	YTPE	DESCRIPTION
1	DAT2	I/O/PP	DATE LINE(BIT2)
2	CD/DAT3	I/O/PP	CARD DETECT DATE LIN(BIT3)
3	CMD	PP	COMMAND RESPONSE
4	VDD	S	SUPPLY VOLTAGE
5	CLX	I	CLOCK
6	VSS	S	SUPPLY VOLTAGE GROUND
7	DAT0	I/O/PP	DATE LINE(BIT0)
8	DAT1	I/O/PP	DATE LINE(DIT1)

GENERAL TOLERANCE	DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD				BXCONN®
DIM. TOL. X X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 GENERAL ANGLE: ±3°	TITLE: MICRO SD CARD PUSH PUSH SMT 镀金 外焊				
	DWG. NO.: TF03−TD9P			DRAWN: MAX	
	PART NO.: TF03−TD9P			CHECKED: ELLA	
	UNIT: mm	SCALE: none	SHEET: 1of 1	DWG. SIZE: A4	LAYER: bxconn	APPROVED: WILL